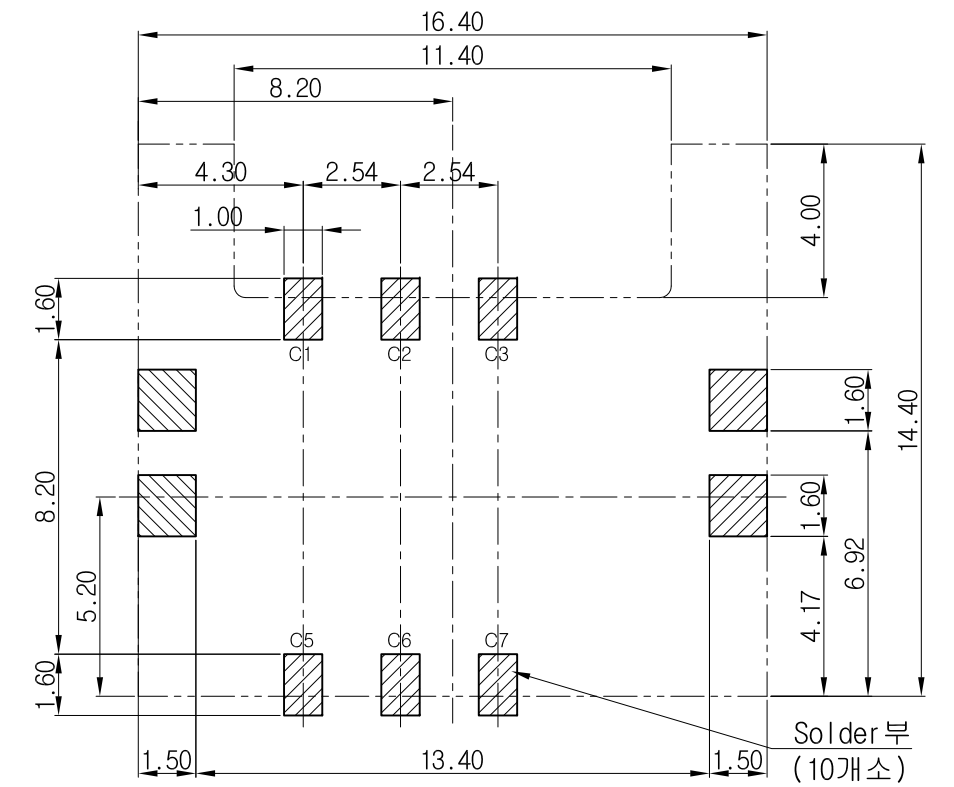
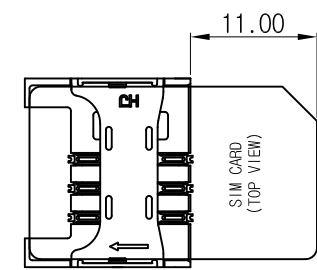
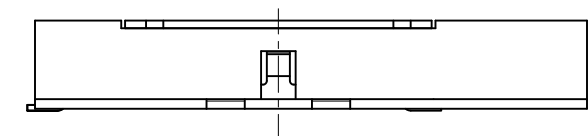
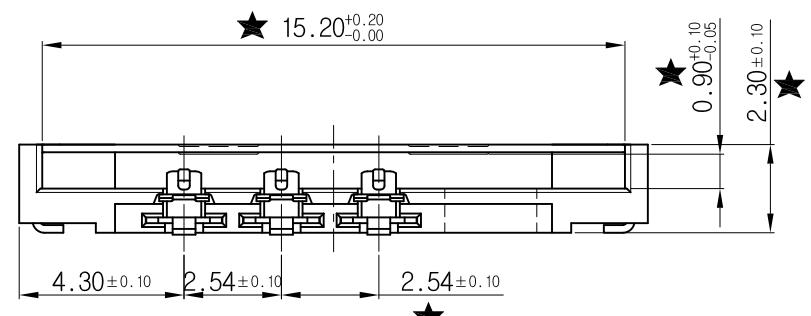


Section A-A'

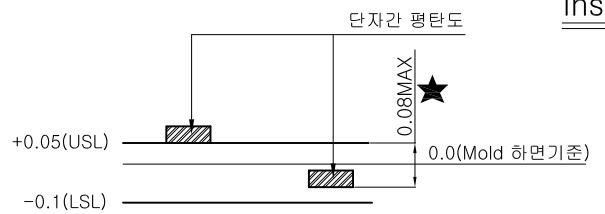
NO.	Description of Revision	Date	Name	Approval	EC NO.
X 1	고객 요청으로 인한 점접 Point 변경	2005 .10 .18	m.g. Son		
X 3	Housing Resin 변경(PA9T GN2330-1 -> LCP L304T40) Housing Stopper 강도보강 Round 추가	2007 .10 .03	m.g. Son		071003-01
X 1	Housing Card Stopper 살보강(0.40->0.44 Min.)	2008. 05. 30	m.g. Son	K.Y. Choi	080530-01
X 1	Card Stopper 부러짐 방지를 위한 Housing Resin 변경 (LCP L304T40 -> HT3 XE3996)	2008. 09. 18	m.g. Son	K.Y. Choi	080918-01



P.C.B Layout (Top View)
Tolerance : ±0.05

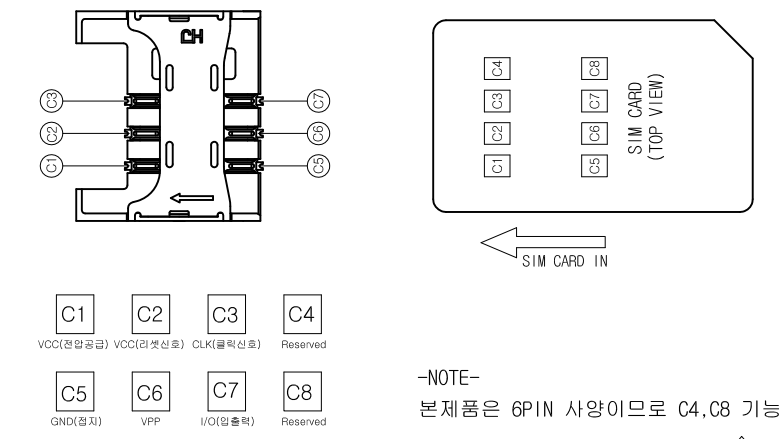


Insert SIM Card



-NOTE-
1. 지시하지 않은 공차 : ±0.10
2. ★ = C.T.Q

단자설명 및 구조해석



No.	Part Name	Material	Finish	Remarks
1	Housing	Thermoplastic(Black)	UL94 HB	PA9T (KUBANA) LCP L304T40
2	Contact Ter'	Beryllium Copper Alloy	Ni:1.0-5.0um/Flash Au:0.05um/Min. Selective Au:0.3um/Min.	BeCuR07-HT (NGK)
3	Metal Cover	Stainless Steel	Ni:1.0-5.0um	STS304CSP-1/2H (TAIHAN)

General Tolerance		Scale	N/S	mm	DRAWN				5000 USIM Series	
Dimension	mm	Date	2005.04.11		M.G.Son				5000-6P-2.3(M)	
0.	±0.2	Drawn	Design	Check	Review	Approval	S / N		A5100656.DWG	Rev'No.
0.0	±0.1					D / N		HSA51-00656	4	
0.00	±0.05									
0.000	±0.01									
0.0000	±0.005									

HJ&C HYUP JIN I&C CO., LTD.